

FORM PTO-1449 (SUBSTITUTE) U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE INFORMATION DISCLOSURE STATEMENT BY APPLICANT (37 CFR 1.98(b))				Attorney Docket No.: Appl. No. GR 97 P 6457 Applicant JÖRG BERTHOLD ET AL. Filing Date Group Art Unit June 16, 2000			
EXAMINER INITIALS	PATENT NO.	DATE	PATENTEE	CLASS	SUB CLASS	FILING DATE	
<i>an</i>	A	5,025,741	06/91	Suwanai et al.			
<i>an</i>	B	5,723,382	03/98	Sandhu et al.			
	C						
	D						
	E						
	F						
	G						
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	I						
FOREIGN PATENT DOCUMENT							
	DOCUMENT NO.	DATE	COUNTRY	CLASS	SUB CLASS	TRANSL. YES NO	
<i>an</i>	J	19543540C1	11/98	Germany			X
<i>an</i>	K	0751566A2	01/97	Europe			X
<i>an</i>	L	0261846A1	03/88	Europe			X
	M						
	N						
OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)							
<i>an</i>	"Barrier Metal Free Copper Damascene Interconnection Technology Using Atmospheric Copper Reflow and Nitrogen Doping in SiOF Film", K. Mikagi et al., IEEE, 1996, pp. 365-368						
<i>an</i>	"Evaluation of a Copper Metallization Process and the Electrical Characteristics of Copper-Interconnected Quarter-Micron CMOS", Nobuyoshi Awaya et al., IEEE Transactions on Electron Devices, Vol. 43, No. 8, August 1996, pp. 1206-1212						
EXAMINER				DATE CONSIDERED			
<i>29/01</i>				<i>8-22-01</i>			
EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.							

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		"Integration of copper multilevel interconnects with oxide and polymer interlevel dielectrics", Ronald J. Gutmann et al., Thin Solid Films 270, 1995, pp. 472-479					
		/					
EXAMINER				DATE CONSIDERED			
				08-22-01			
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